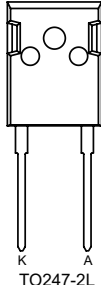



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D101200W	TO247-2L	WNSC2D101200WQ	Tube	30	TO247L-2L	10-Nov-2020

7. Marking

Table 4. Marking codes

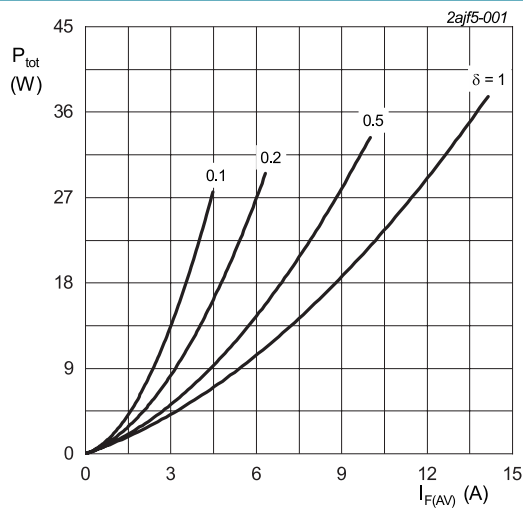
Type number	Marking codes
WNSC2D101200W	WNSC2D 101200W

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		1200	V
V_{RWM}	crest working reverse voltage		1200	V
V_R	reverse voltage	DC	1200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 132\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	10	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 132\text{ }^\circ\text{C}$; square-wave pulse	20	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse	72	A
		$t_p = 10\text{ }\mu\text{s}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; square-wave pulse	850	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; $t_p = 10\text{ ms}$	26	A^2s
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.041\text{ V}; R_s = 0.1148\text{ }\Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

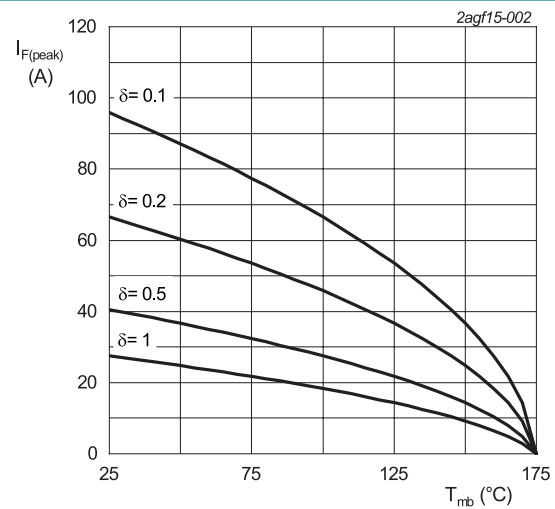
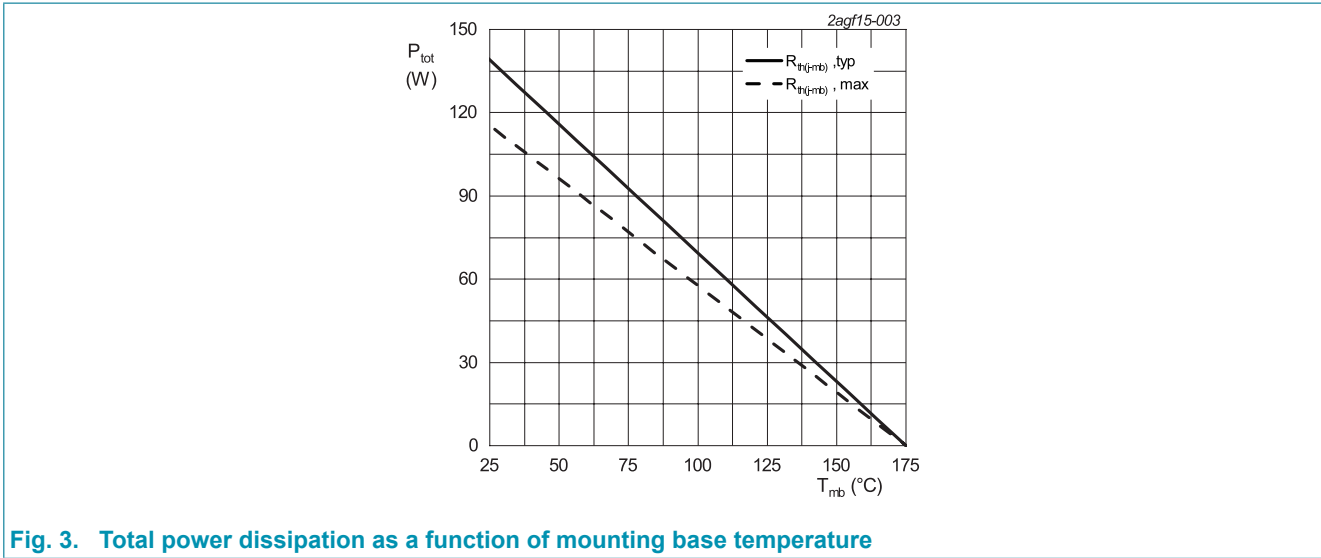


Fig. 2. Current derating as a function of mounting base temperature



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4	-	1.08	1.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	40	-	K/W

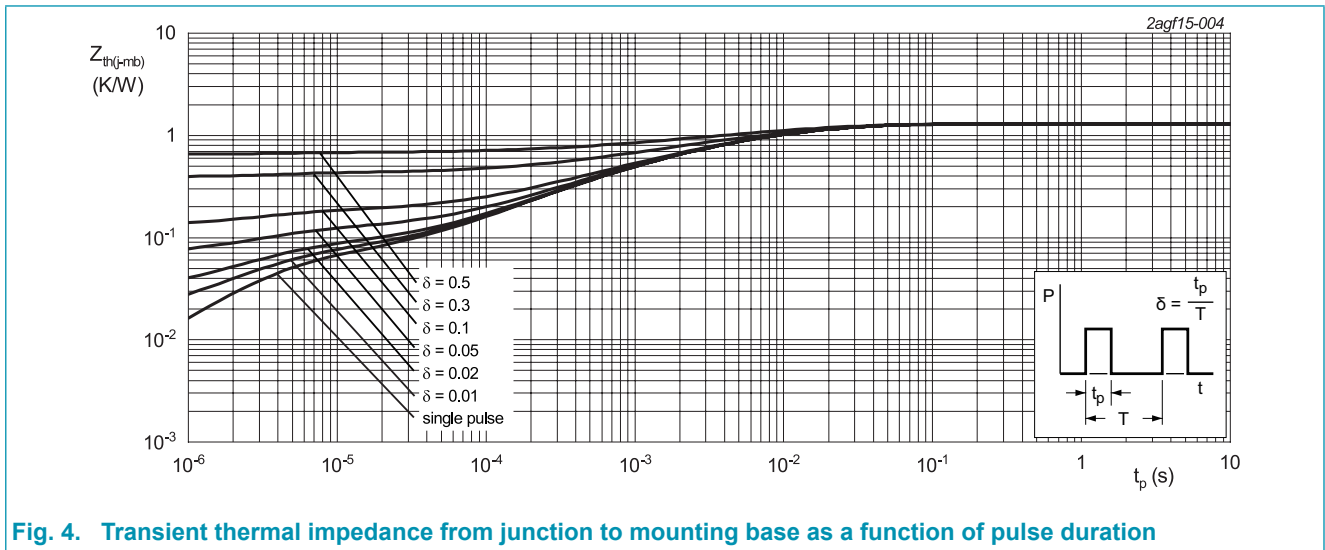
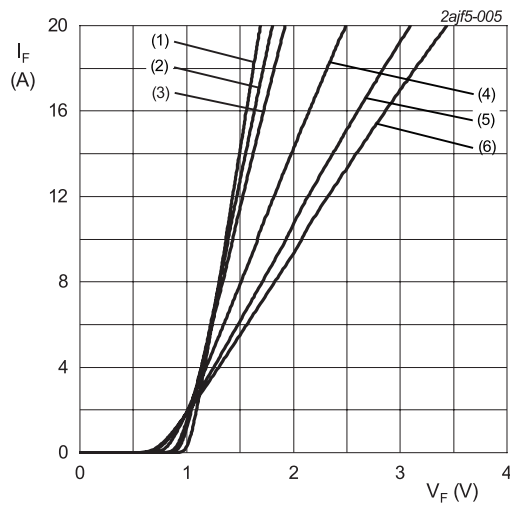


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_F	forward current	$I_F = 10 \text{ A}; T_J = 25 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	1.42	1.65	V
		$I_F = 10 \text{ A}; T_J = 150 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	1.88	2.3	V
		$I_F = 10 \text{ A}; T_J = 175 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	1.97	2.5	V
I_R	reverse current	$V_R = 1200 \text{ V}; T_J = 25 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	3	110	μA
		$V_R = 1200 \text{ V}; T_J = 175 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	60	-	μA
Dynamic characteristics						
Q_r	recovered charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s}; T_J = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	25	-	nC
C_d	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	490	-	pF
		$f = 1 \text{ MHz}; V_R = 400 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	48	-	pF
		$f = 1 \text{ MHz}; V_R = 800 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	36	-	pF
E_{as}	non-repetitive avalanche energy	$I_R = 4.2 \text{ A}; L = 10 \text{ mH}; T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$	88	-	-	mJ



$V_o = 1.041 \text{ V}; R_s = 0.1148 \text{ } \Omega$
 (1) $T_J = -55 \text{ }^\circ\text{C};$ typical values
 (2) $T_J = 0 \text{ }^\circ\text{C};$ typical values
 (3) $T_J = 25 \text{ }^\circ\text{C};$ typical values
 (4) $T_J = 100 \text{ }^\circ\text{C};$ typical values
 (5) $T_J = 150 \text{ }^\circ\text{C};$ typical values
 (6) $T_J = 175 \text{ }^\circ\text{C};$ typical values

Fig. 5. Forward current as a function of forward voltage; typical values

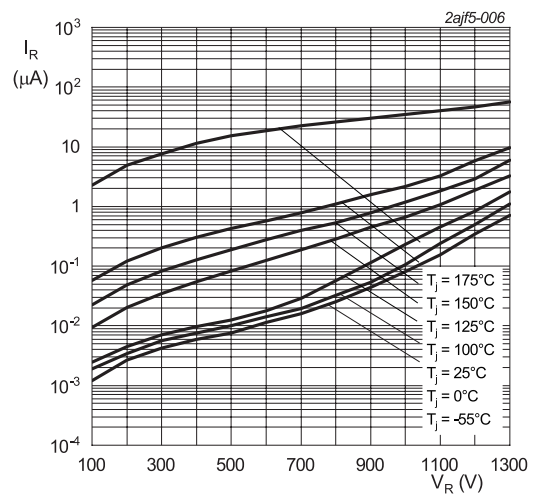


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

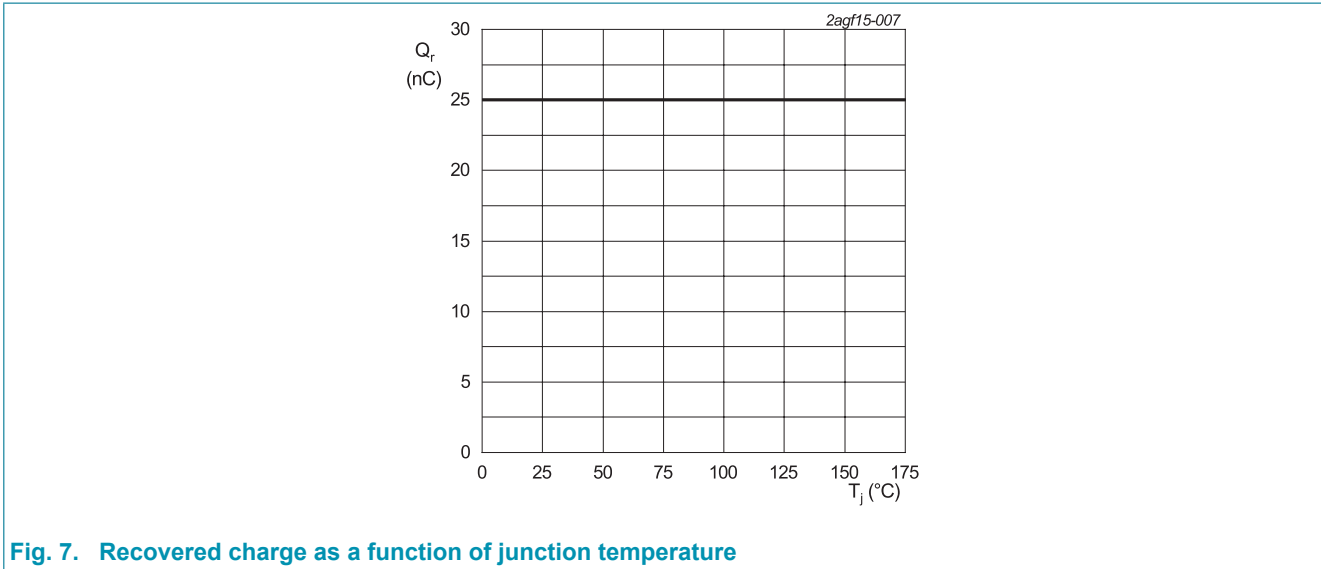
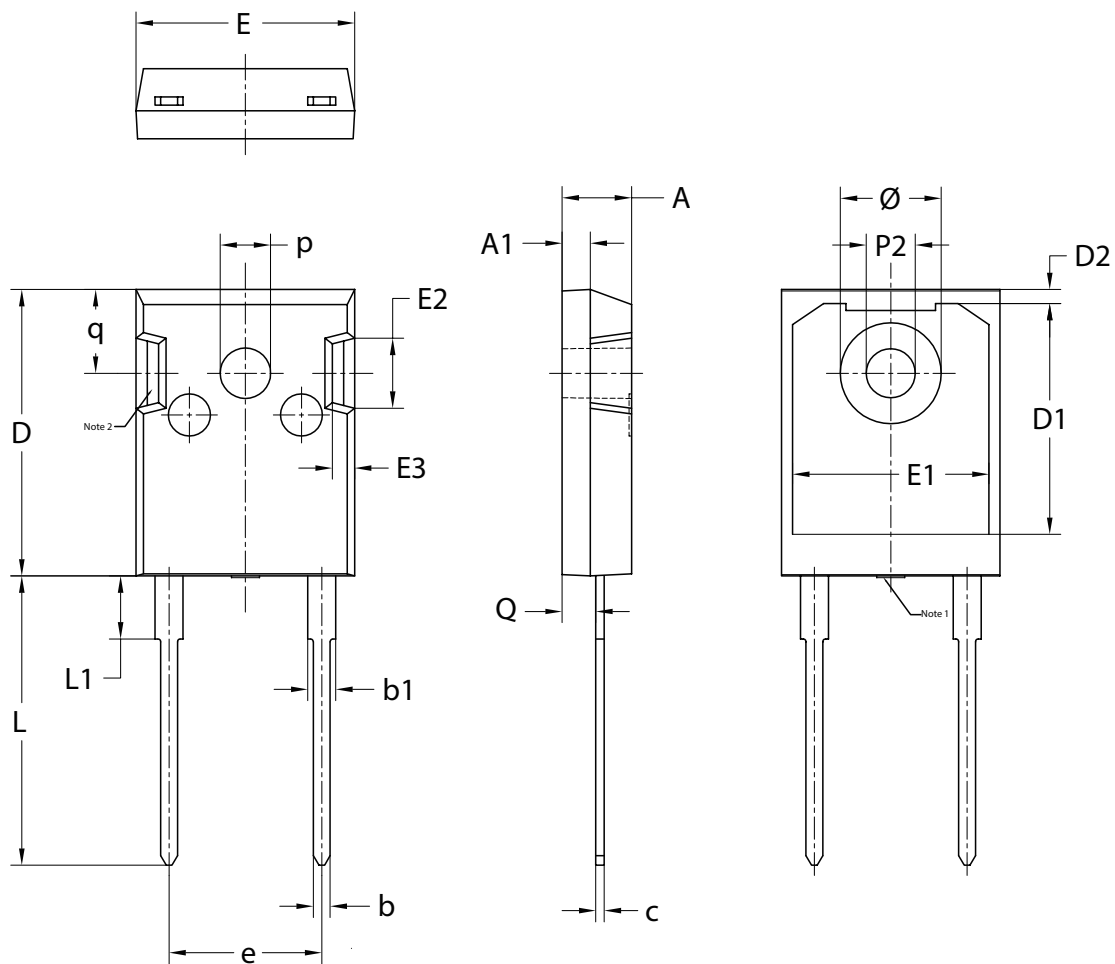


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



UNIT	A	A ₁	b	b ₁	c	D	D ₁ Ⓜ	D ₂	E	E ₁	E ₂	E ₃	e	L	L ₁	P ₂	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

Note:

1. Mold resin protrusion max 0.127mm.
2. Metal exposed with Sn plating.

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 12 November 2020
